

Title (en)  
EPOXY IMPREGNATED TAPE BACKING.

Title (de)  
EPOXY IMPREGNIERTE BANDRÜCKSCHICHT.

Title (fr)  
MATERIAU DE SUPPORT POUR BANDES IMPREGNE D'UNE COMPOSITION EPOXY.

Publication  
**EP 0680657 A1 19951108 (EN)**

Application  
**EP 93920469 A 19930901**

Priority  
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Abstract (en)  
[origin: WO9409497A1] The present invention relates to a flexible tape backing comprising a substrate which has coated thereon a photopolymerized epoxy composition containing a plurality of epoxides including at least one selected from the group consisting of bisphenol A epoxides and cycloaliphatic epoxides, and at least one aliphatic epoxide, from 0.1 % to 2 % of at least one organometallic cationic initiator capable of initiating polymerization at wavelengths of from 200 to 600 nm, and at least one accelerating agent, wherein said backing is fully cured after an irradiation of from 1 to 15 seconds, without a heating step.

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IPC 8 full level  
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